

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (original): A method for preparing an on-spot hydrophilic enhanced slide, comprising the steps of:

- a) preparing a hydrophobic copolymer in a solvent to obtain a solution of hydrophobic copolymer;
- b) coating said solution of hydrophobic copolymer onto a substrate; and
- c) removing said solvent.

Claim 2 (original): The method as claimed in claim 1, wherein the hydrophobic copolymer is prepared by blending, grafting or co-polymerization of a hydrophobic material and a compound bearing a functional group selected from the group consisting of anhydride, imide, cyclic amide, and cyclic ester.

Claim 3 (original): The method as claimed in claim 2, wherein the hydrophobic material is selected from the group consisting of styrene, urethane, ethylene, and derivatives thereof.

Claim 4 (original): The method as claimed in claim 3, wherein the hydrophobic copolymer comprises poly(styrene-co-maleic anhydride), poly(styrene-co-maleimide), or poly(ethylene-co-maleic anhydride).

Claim 5 (original): The method as claimed in claim 1, wherein the substrate comprises organic or inorganic substrate.

Claim 6 (original): The method as claimed in claim 5, wherein the organic substrate comprises a polymer polymerized by organic monomers, wherein said organic monomers is selected from the group consisting of a monomer of ethylene, styrene, propylene, ester, acrylic acid, acrylate, alkyl acrylic acid, and alkyl acrylate.

Claim 7 (original): The method as claimed in claim 6, wherein the organic substrate comprises substrate consisting of poly(styrene-co-maleic anhydride), poly(styrene-co-maleimide), or poly(ethylene-co-maleic anhydride).

Claim 8 (original): The method as claimed in claim 5, wherein the inorganic substrate comprises silicon wafer, ceramic material, glass, or metal.

Claim 9 (original): The method as claimed in claim 1, further comprising activating the substrate surface prior to the coating step.

Claim 10 (original): The method as claimed in claim 9, wherein the activating step is treating the substrate surface with an acid or a base, or treating the substrate surface by plasma activation.

Claim 11 (original): The method as claimed in claim 10, wherein the substrate is an inorganic substrate.

Claim 12 (original): The method as claimed in claim 1, further comprising cleaning the substrate surface before step (b).

Claim 13 (original): The method as claimed in claim 12, wherein the cleaning step is performed by the pretreatment with a solvent and/or sonication.

Claim 14 (original): A method as claimed in claim 13, wherein the solvent is selected from the group consisting of surfactant, water, alcohol, and acetone.

Claim 15 (original): The method as claimed in claim 1, wherein the coating step comprises spin coating, screen printing, roller coating, curtain coating, or dip coating.

Claim 16 (original): The method as claimed in claim 15, wherein the coating step is spin coating.

Claim 17 (original): The method as claimed in claim 1, wherein the step of removing solvent comprises vacuum evaporation, heating evaporation, or evaporation under reduced pressure.

Claim 18 (original): The method as claimed in claim 17, wherein the heating evaporation is carried out at a temperature not higher than 100°C.

Claims 19-26 (cancelled)